

ABSTRACT OF THE DISCLOSURE

A vertical routing structure for a multi-layered substrate having a lamination structure therein. The lamination structure has at least a through hole that links up both surfaces of the lamination structure. The vertical routing structure comprises a
5 conductive rod and a conductive layer. The conductive rod is formed inside the through-hole with the ends protruding above the respective upper and lower surface of the lamination structure. The conductive layer is positioned in the space between the interior sidewall of the through-hole and the conductive rod. The vertical routing structure on the substrate is able to reduce the area for laying the required circuits or increase the wiring
10 density in a given area.